



CALL FOR PAPERS

IMPORTANT DATES

Paper Submission Deadlines

February 10, 2025

Option B: Submit to IEEE Sensors Letters

March 3, 2025

Option A: Submit to IEEE FLEPS 2025 Proceedings

April 18, 2025

Notification of Acceptance

May 2, 2025

Final Manuscript Submission Deadline

ORGANIZERS

General Co-Chairs

Benjamin Tee

National University of Singapore,
Singapore

Nanshu Lu

University of Texas, Austin, USA

Technical Program Co-Chairs

Wei Gao

CALTECH, USA

Changsheng Wu

National University of Singapore,
Singapore

Oversight Committee

Ravinder Dahiya

Northeastern University, Boston, USA

Luigi G. Occhipinti

Cambridge University, UK

Kouros Kalantar-Zadeh

University of Sydney, Australia

The IEEE International Conference on Flexible, Printable Sensors and Systems (FLEPS 2025) will be held in Singapore.

IEEE FLEPS 2025 is intended to provide a forum for research scientists, engineers, and practitioners throughout the world to present their latest research findings, ideas, and applications in the area of Flexible and Printable Sensors and Systems.

TOPICS OF INTEREST

- » Organic/Inorganic Electronics and Sensors
- » Materials and Design for Flexible, Stretchable, and Printed Systems
- » Advanced Manufacturing Techniques
- » High-throughput Printable Electronics
- » Hybrid Systems and Heterogeneous Integration
- » Stretchable/Shrinkable Sensors and Electronics
- » Wearable and Implantable Systems
- » Degradable/Reusable Sensors and Systems
- » Printed Large-Area Sensors and Systems
- » Active and Passive Components (e.g. actuators, printed energy devices, smart labels, RFID etc.)
- » Emerging applications of Flexible Electronics in AI, Robotics, Cognitive Systems, IoT, smart cities etc.
- » Reliability, Simulation and Modelling
- » Electronics for Sustainability
- » Standards for Flexible and Stretchable Electronics

For further information, contact **Claire Folkerts** at Conference Catalysts, LLC.

